



US00D971862S

(12) **United States Design Patent**
Inagaki et al.

(10) **Patent No.:** **US D971,862 S**
(45) **Date of Patent:** **** Dec. 6, 2022**

(54) **HEATSINK**

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(73) Assignee: **Furukawa Electric Co., Ltd.**, Tokyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/696,679**

(22) Filed: **Jun. 28, 2019**

(30) **Foreign Application Priority Data**

Dec. 28, 2018 (JP) 2018-28918

(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 182; D23/231; D14/230
CPC . H01Q 1/428; H01Q 1/02; H01Q 1/38; H01L 23/367; H01L 23/3672; H05K 7/20254; F28F 3/022; F28F 3/04; F28F 21/065; G02B 1/111; F28D 15/0275
See application file for complete search history.

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(57) **CLAIM**

We claim the ornamental design for a heatsink, as shown and described.

DESCRIPTION

FIG. 1 shows a top isometric view of a heatsink in accordance with the present design.

FIG. 2 shows a bottom isometric view of the heatsink in FIG. 1.

FIG. 3 shows a top view of the heatsink in FIG. 1.

FIG. 4 shows a bottom view of the heatsink in FIG. 1.

FIG. 5 shows a right side view of the heatsink in FIG. 1.

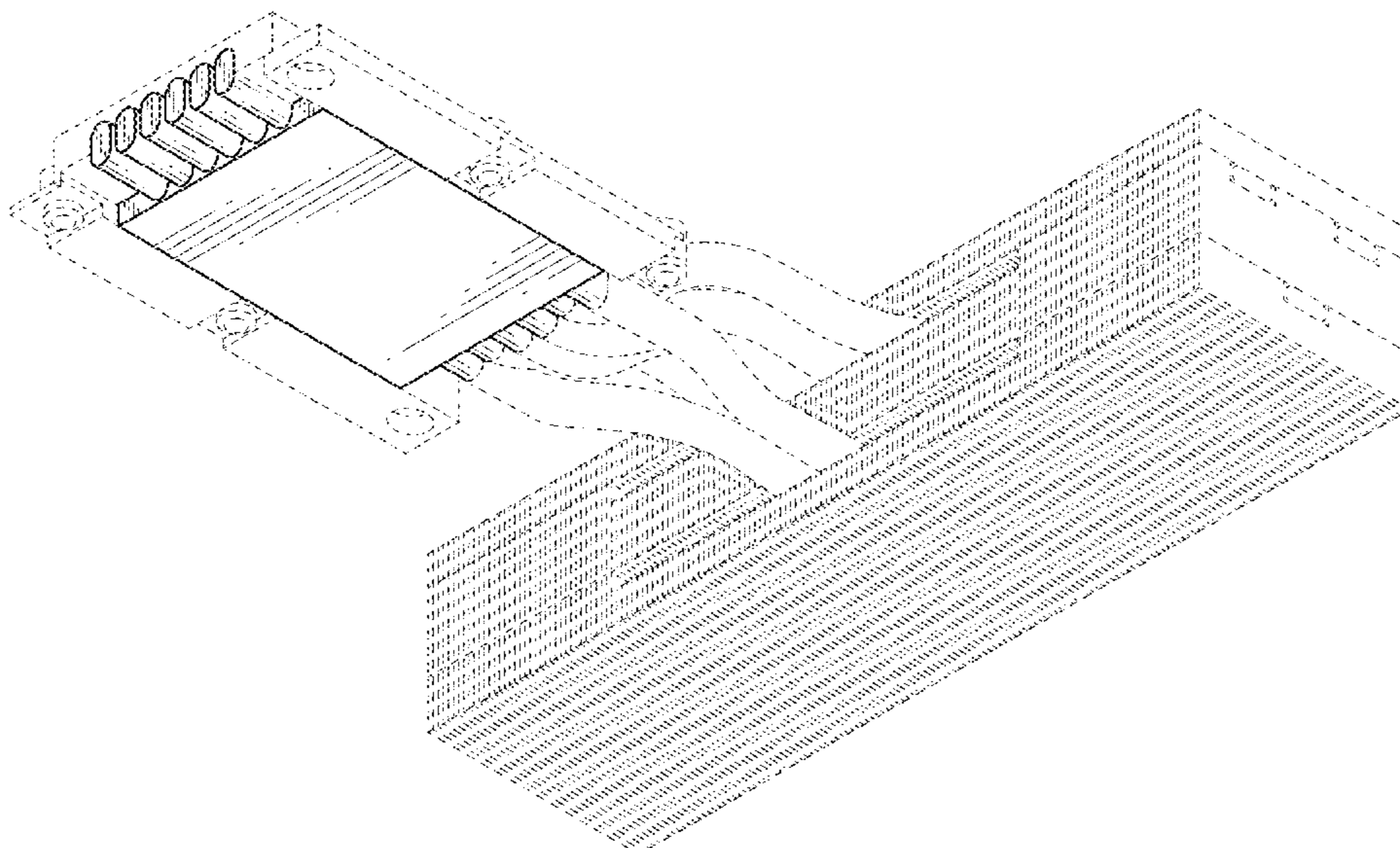
FIG. 6 shows a left side view of the heatsink in FIG. 1.

FIG. 7 shows a front view of the heatsink in FIG. 1; and,

FIG. 8 shows a rear view of the heatsink in FIG. 1.

The even broken lines illustrate environment and form no part of the claimed design. The dot-dash broken lines represent boundary lines and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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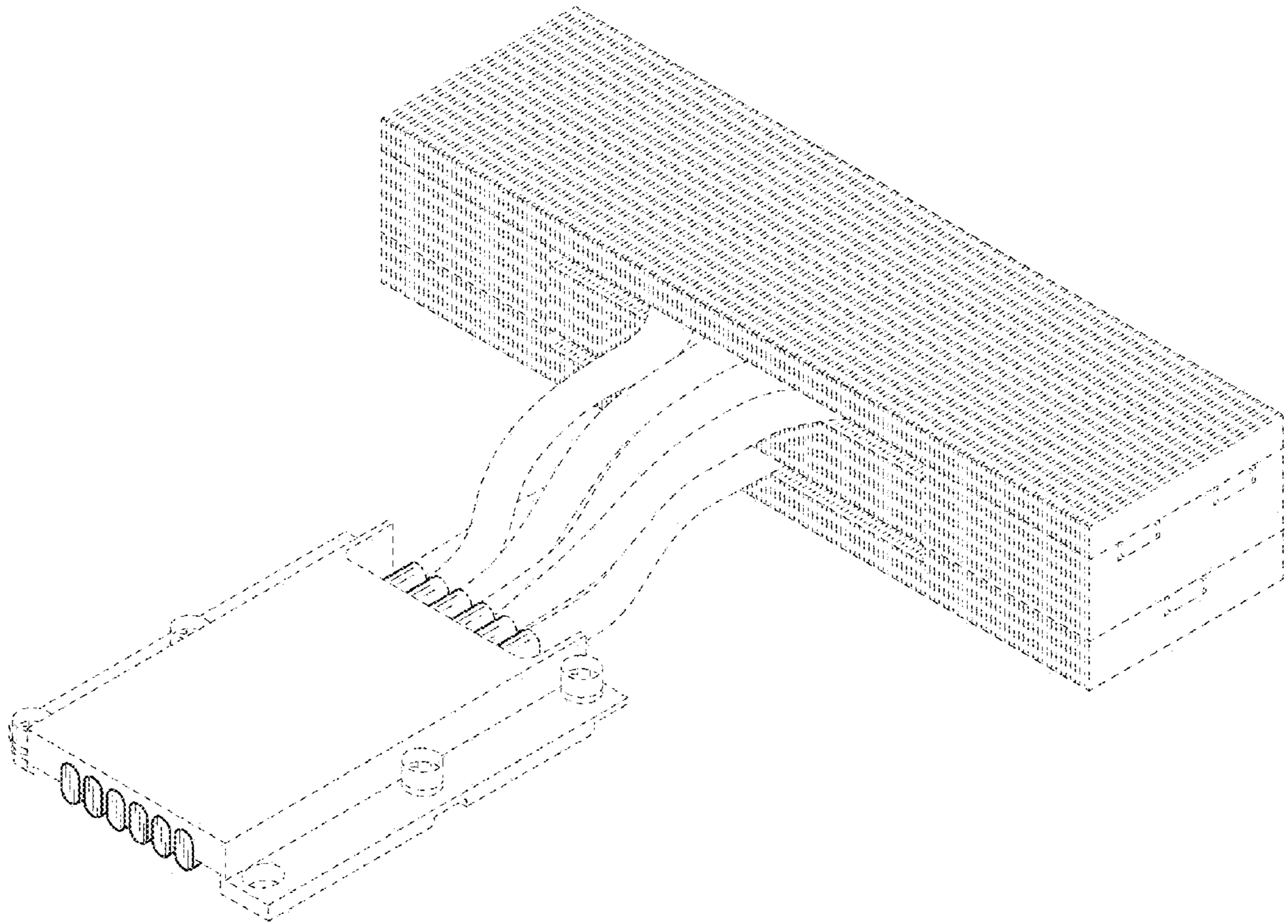


FIG. 1

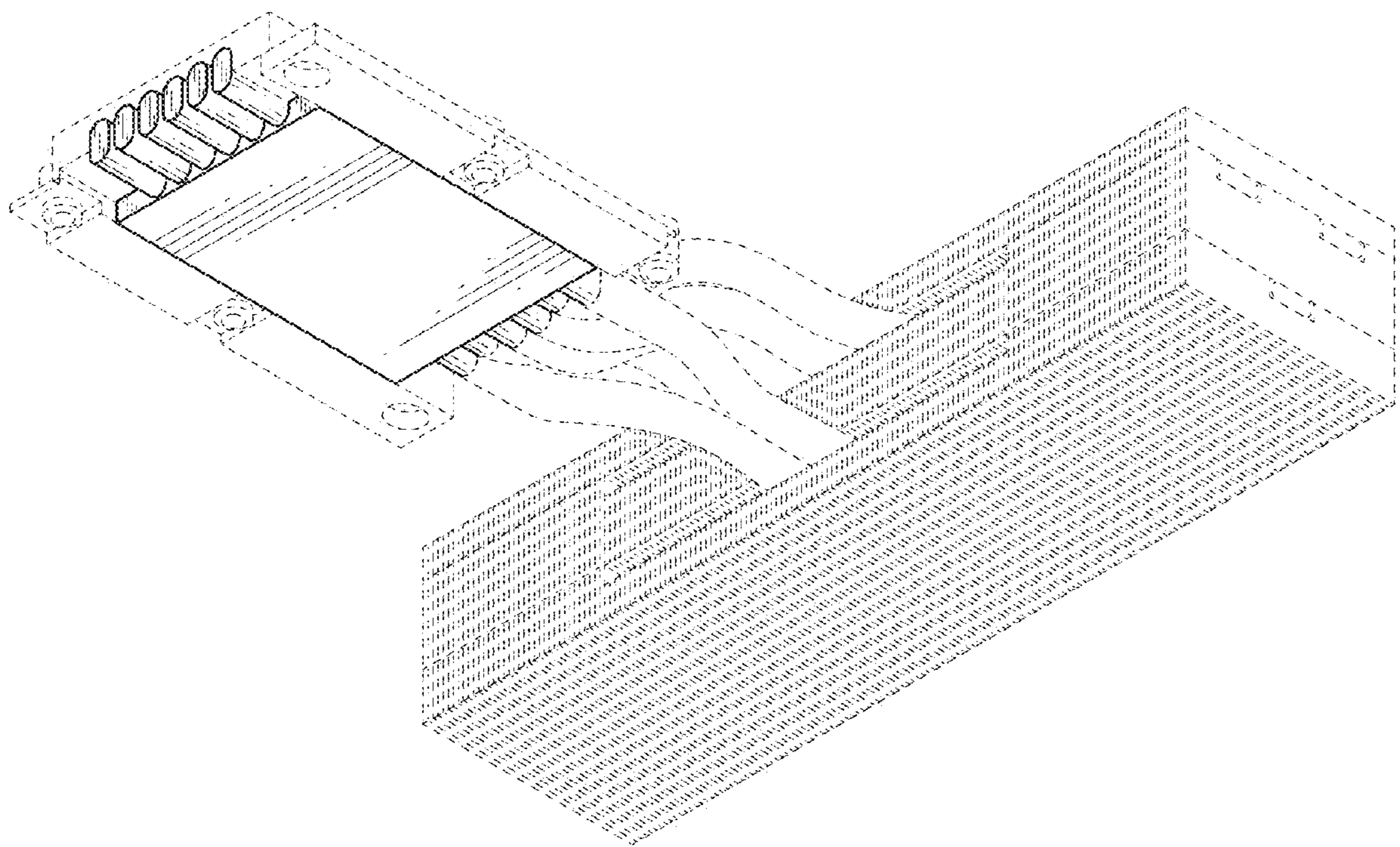


FIG. 2

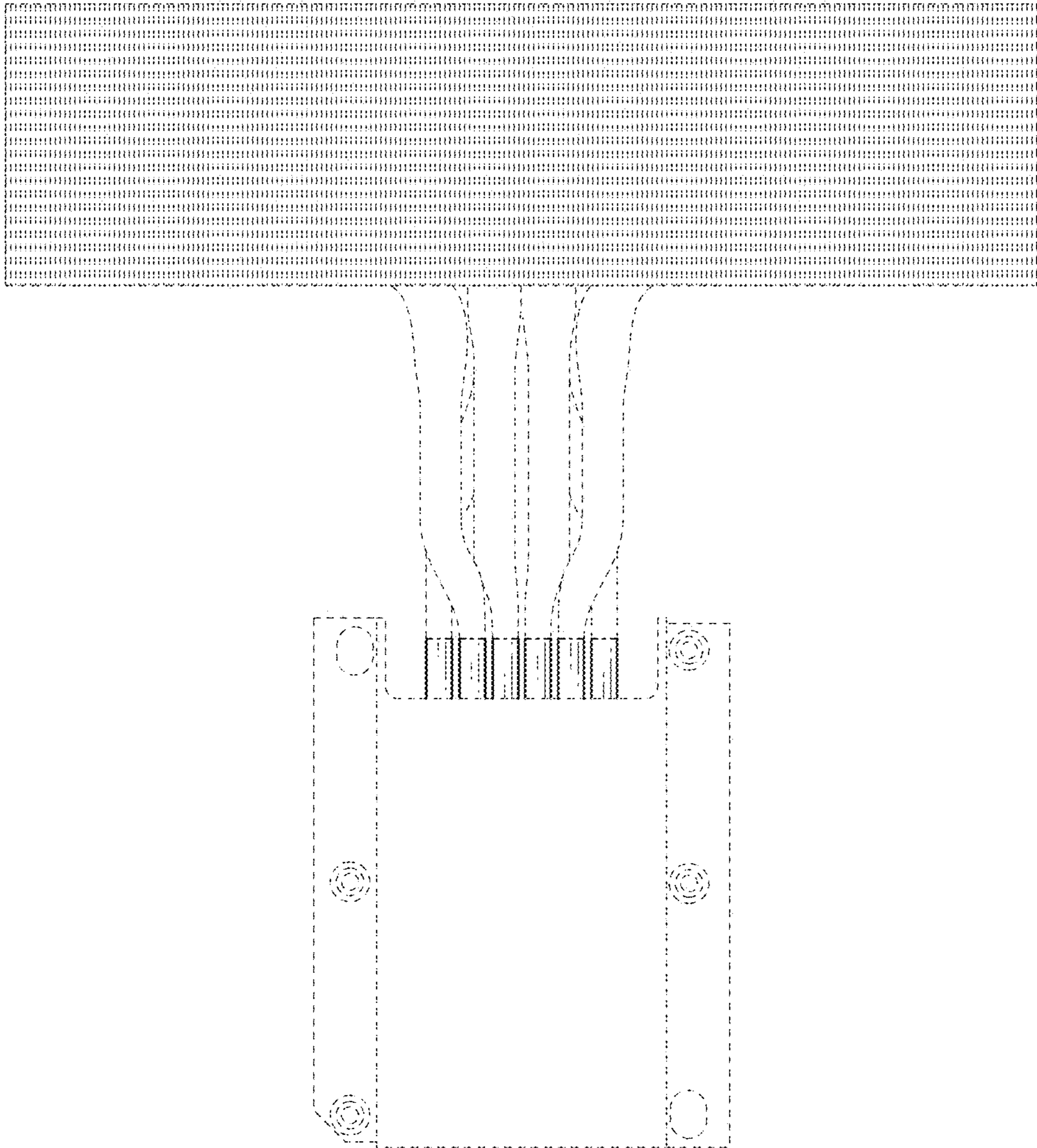


FIG. 3

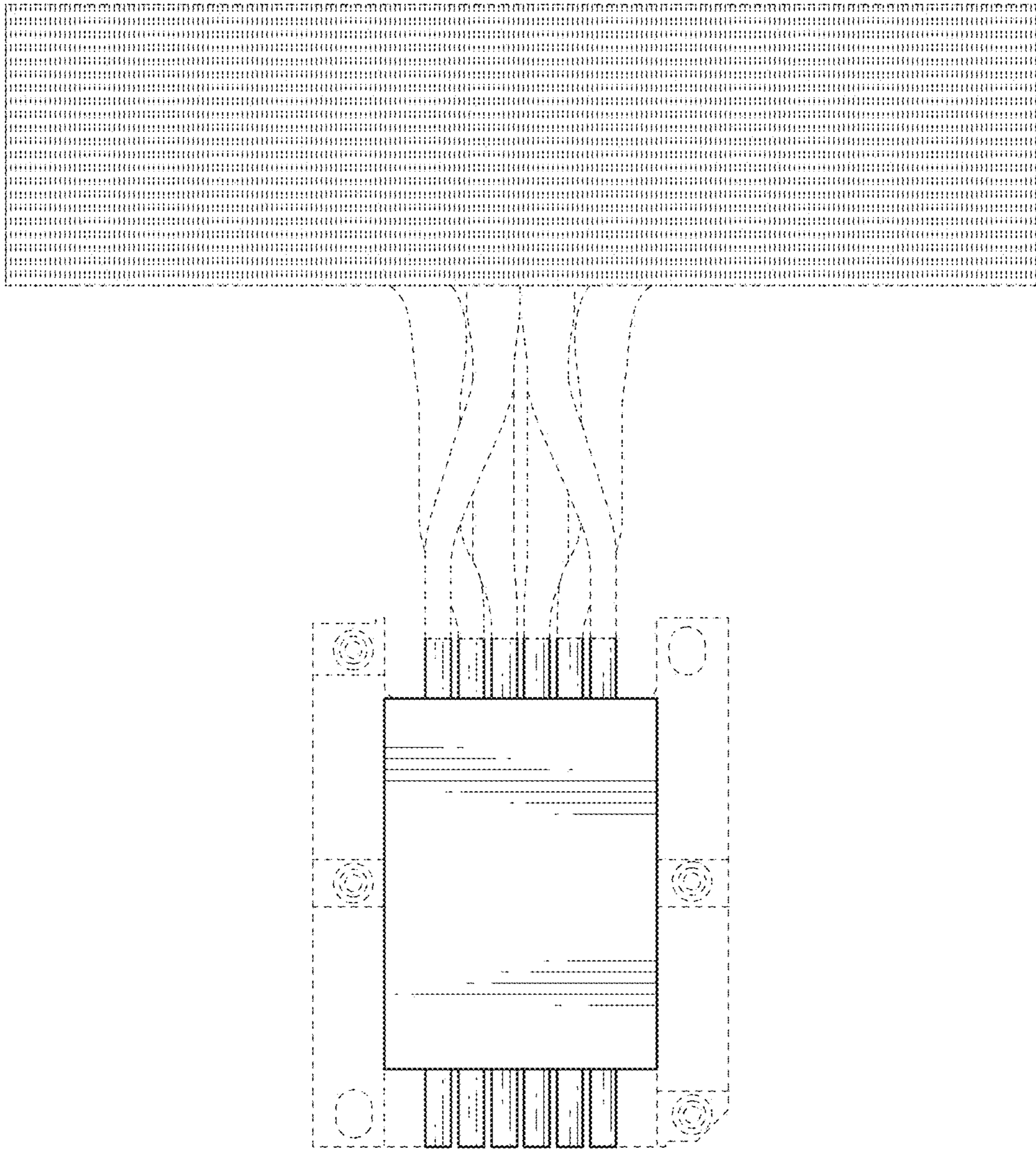


FIG. 4

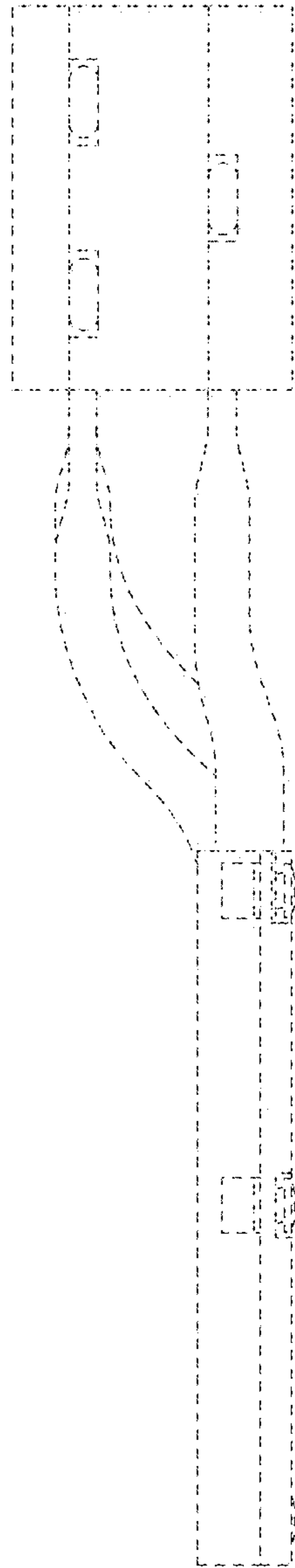


FIG. 5

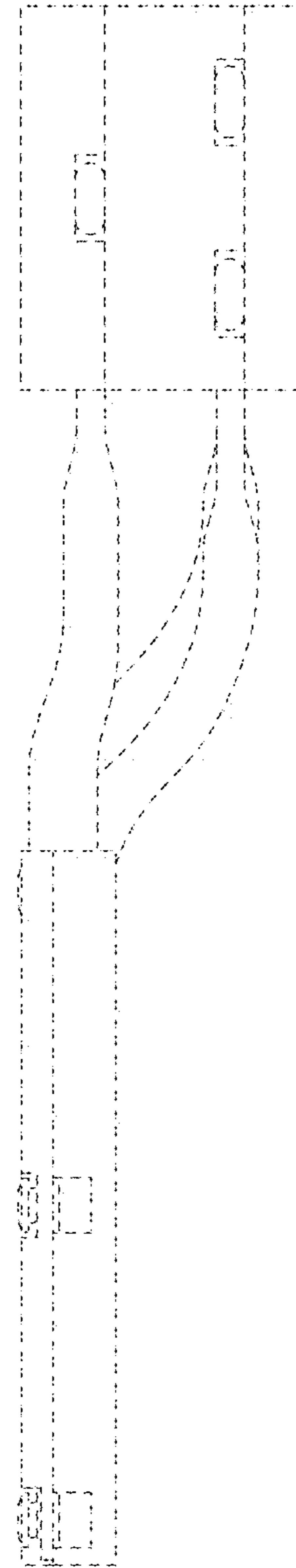


FIG. 6

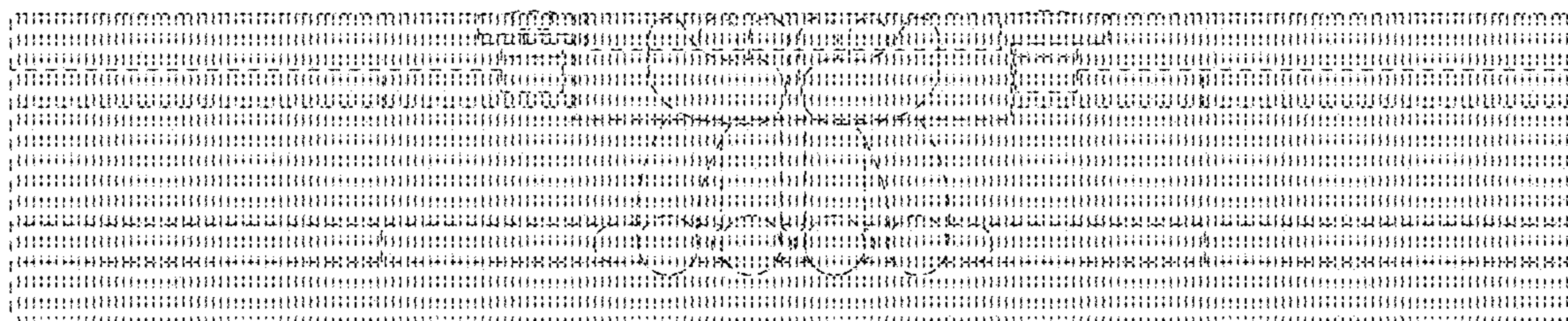


FIG. 7

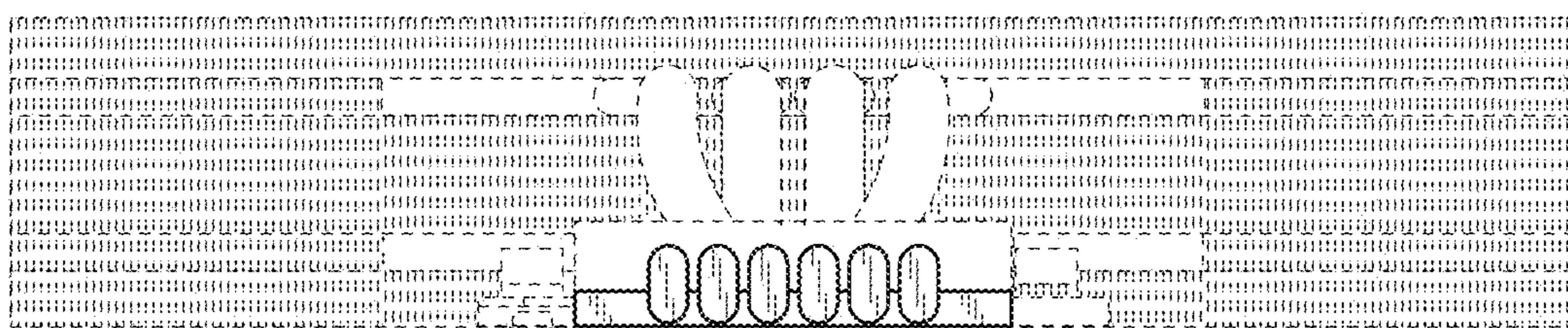


FIG. 8